## **SMD CAPACITORS**

Type/ Series	Voltage (V)	Capacitance (µF)	Tol (+/-%)	Dissipation Factor	Case Sizes	Application Notes
Multilayer Ceramic CE	16 - 2000	0.5pF- 6.8µF	0.1pf - 20%	.02% - 4%	0201 - 3035	Wide range of sizes, tolerance, TC, and voltage. High reliability, and excellent frequency response.
Tantalum TS, SAT	2.7 - 50	0.1μF - 330μF	10% - 20%	4% - 12%	0805 - 7343	Epoxy Molded, UL94V-0 flame retardant. Superior humidity and solder resist. Sinter-Anode is type SAT.

## **SMD COILS & INDUCTORS**

Type/ Series	Inductance (µH)	Tolerance (%)	SRF Min. (MHz)	DCR Max. (Ohms)	Rated Current (mA)	Case Sizes	Application Notes
Multilayer Ceramic MLI	.047 - 33µH	0.3nH - 20%	13 - 680	0.15 - 4.7	5 - 110	0603 - 1206	Multilayer structure provides outstanding reliability. Excellent Q and SRF char.
Multilayer 'High Frequency' MHI	1.0 - 470µH	0.3nH - 20%	430 - 12,000	0.1 - 1.2	200 - 500	0402 - 0805	Advanced monolithic construction suited especially for higher frequency applications.
Minature Wirewound 'Open Core'	.0056 - 10µH	5% - 20%	60 - 6000	0 .04 - 4.0	210 - 1410	0805 - 1008 *	Small package size. Flat-top design avail. Suitable for reflow soldering. '0603' size in devel. *
Molded Wirewound MCI	.01 - 1000μH	5% - 20%	2.5 - 2500	0.13 - 40.0	30 - 480	1210 - 1812	Molded construction Excellent protection. New higher current sizes available.
Molded 'Shielded' Wirewound MSI	0.1 - 1000μH	5% - 20%	2.0 - 460	0.23 - 16.0	15 - 450	1812	Electromagnetic shielding. Molded construction. Mini-sizes in develop.
High Power, Low Profile HI330	1.0 - 1000µH	20%	2.0 - 100	.008 - 2.15	up to 20A	.510 x .370	Low profile. High performance. Low DC resistance. High power-to-size.
High Power, Shielded HI500	10.0 - 1000µH	20%	2.0 - 30	.04 - 2.01	up to 8A	.730 x .600	Shielded construction Low DC resistance. Cost effective.
Power Inductor Coil PIC	0.68 - 2200μH	5% - 20%	Consult Factory	.04 - 5.46	up to 3.5A	.189 - .433	Wide range of sizes. Low profile, and cost. Excellent high freq.